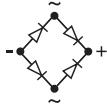


CBRHD-01

**SURFACE MOUNT SILICON
HIGH DENSITY
0.8 AMP
BRIDGE RECTIFIER**

HDBRIDGE



HD DIP CASE



www.centrasemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CBRHD-01 is a silicon full wave bridge rectifier mounted in a durable epoxy surface mount molded case, utilizing glass passivated chips.

MARKING CODE: CBD1

FEATURES:

- Efficient use of board space: requires only 42mm² of board space vs. 120mm² of board space needed for industry standard 1.0 Amp surface mount bridge rectifier.
- 50% higher density (Amps/mm²) than the industry standard 1.0 Amp surface mount bridge rectifier.
- Glass passivated chips for high reliability.

MAXIMUM RATINGS: (T_A=25°C unless otherwise noted)

Peak Repetitive Reverse Voltage

DC Blocking Voltage

RMS Reverse Voltage

Average Forward Current (T_A=40°C) (Note1)

Average Forward Current (T_A=40°C) (Note 2)

Peak Forward Surge Current

Operating and Storage Junction Temperature

Thermal Resistance (Note 3)

SYMBOL

V_{RRM}

V_R

V_{R(RMS)}

I_O

I_O

I_{FSM}

T_J, T_{stg}

Θ_{JA}

100

100

70

0.5

0.8

30

-65 to +150

85

UNITS

V

V

V

A

A

A

°C

°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	TYP	MAX	UNITS
I _R	V _R = 100V		5.0	μA
I _R	V _R = 100V, T _A =125°C		500	μA
V _F	I _F =400mA		1.0	V
C _J	V _R =4.0V, f=1.0MHz	9.0		pF

Notes: (1) Mounted on Glass-Epoxy PCB.

(2) Mounted on Ceramic PCB.

(3) Mounted on PCB with 0.5" x 0.5" copper pads.

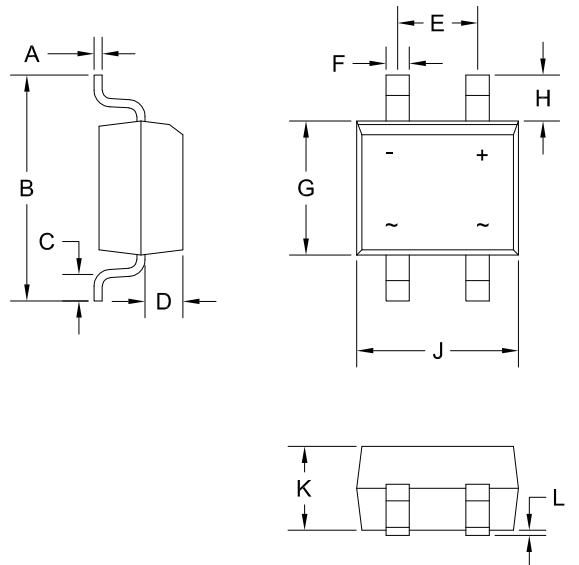
R4 (19-August 2020)

CBRHD-01

SURFACE MOUNT SILICON
HIGH DENSITY
0.8 AMP
BRIDGE RECTIFIER



HD DIP CASE - MECHANICAL OUTLINE



R3

DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.006	0.014	0.15	0.35
B	-	0.275	-	7.00
C	0.027	0.043	0.70	1.10
D	0.035	0.051	0.90	1.30
E	0.090	0.106	2.30	2.70
F	0.019	0.031	0.50	0.80
G	0.146	0.165	3.70	4.20
H	0.051	0.067	1.30	1.70
J	0.177	0.193	4.50	4.90
K	0.090	0.106	2.30	2.70
L	0.000	0.008	0.00	0.20

HD DIP (REV: R3)

MARKING CODE: CBD1

R4 (19-August 2020)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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